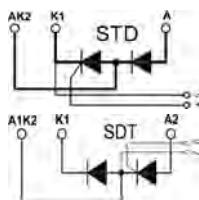


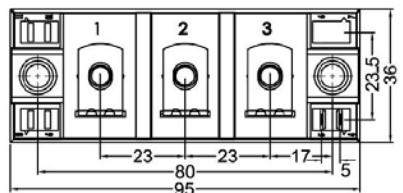
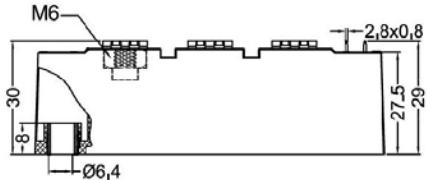
STD181GKXX

Thyristor-Diode Modules



Type	V _{RSM} V _{DSTM} V	V _{RRM} V _{DRM} V
STD181GK08	900	800
STD181GK12	1300	1200
STD181GK14	1500	1400
STD181GK16	1700	1600
STD181GK18	1900	1800

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit	
I _{TRMS} , I _{FRMS} I _{TAVM} , I _{FAVM}	T _{VJ} =T _{VJM} T _C =85°C; 180° sine	300 181	A	
I _{TSM} , I _{FSM}	T _{VJ} =45°C V _R =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine	6000 6400	A	
	T _{VJ} =T _{VJM} V _R =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	5250 5600		
$\int i^2 dt$	T _{VJ} =45°C V _R =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine	180000 170000	A ² s	
	T _{VJ} =T _{VJM} V _R =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	137000 128000		
(di/dt) _{cr}	T _{VJ} =T _{VJM} f=50Hz, t _p =200us V _D =2/3V _{DRM} I _G =0.5A dI _G /dt=0.5A/us	repetitive, I _T =500A non repetitive, I _T =500A	150 500	A/us
(dv/dt) _{cr}	T _{VJ} =T _{VJM} ; V _{DR} =2/3V _{DRM} R _{GK} =∞; method 1 (linear voltage rise)	1000	V/us	
P _{GM}	T _{VJ} =T _{VJM} I _T =I _{TAVM} t _p =30us t _p =500us	120 60	W	
P _{GAV}		8	W	
V _{RGM}		10	V	
T _{VJ} T _{VJM} T _{stg}		-40...+125 125 -40...+125	°C	
V _{ISOL}	50/60Hz, RMS I _{ISOL} ≤1mA	t=1min t=1s	3000 3600	V~
M _d	Mounting torque (M6) Terminal connection torque (M6)	2.25-2.75/20-25 4.5-5.5/40-48	Nm/lb.in.	
Weight	Typical	122	g	

Sirectifier®

STD181GKXX

Thyristor-Diode Modules

Symbol	Test Conditions	Characteristic Values	Unit
I_{RRM}, I_{DRM}	$V_{VJ}=V_{VJM}; V_R=V_{RRM}; V_D=V_{DRM}$	10	mA
V_T, V_F	$I_T, I_F=300A; V_{VJ}=25^\circ C$	1.25	V
V_{TO}	For power-loss calculations only ($T_{VJ}=125^\circ C$)	0.88	V
r_T		1.15	$m\Omega$
V_{GT}	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	2.5 2.6	V
I_{GT}	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	150 200	mA
V_{GD}	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	0.2	V
I_{GD}		10	mA
I_L	$T_{VJ}=25^\circ C; t_p=30\mu s; V_D=6V$ $I_G=0.5A; dI/dt=0.5A/\mu s$	300	mA
I_H	$T_{VJ}=25^\circ C; V_D=6V; R_{GK}=\infty$	200	mA
t_{gd}	$T_{VJ}=25^\circ C; V_D=1/2V_{DRM}$ $I_G=0.5A; dI/dt=0.5A/\mu s$	2	us
t_q	$T_{VJ}=T_{VJM}; I_T=300A; t_p=200\mu s; -dI/dt=10A/\mu s$ $V_R=100V; dv/dt=20V/\mu s; V_D=2/3V_{DRM}$	typ. 150	us
Q_s	$T_{VJ}=T_{VJM}; I_T, I_F=300A; -dI/dt=50A/\mu s$	550	uC
I_{RM}		235	A
R_{thJC}	per thyristor/diode; DC current per module	0.155 0.0775	K/W
R_{thJK}	per thyristor/diode; DC current per module	0.225 0.1125	K/W
ds	Creeping distance on surface	12.7	mm
da	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

FEATURES

- * International standard package
- * DCB base plate
- * Glass passivated chips
- * Isolation voltage 3600 V~
- * UL File NO.E310749
- * RoHS compliant

APPLICATIONS

- * Motor control
- * Power converter
- * Heat and temperature control for industrial furnaces and chemical processes
- * Lighting control
- * Contactless switches

ADVANTAGES

- * Space and weight savings
- * Simple mounting
- * Improved temperature and power cycling
- * Reduced protection circuits

STD181GKXX

Thyristor-Diode Modules

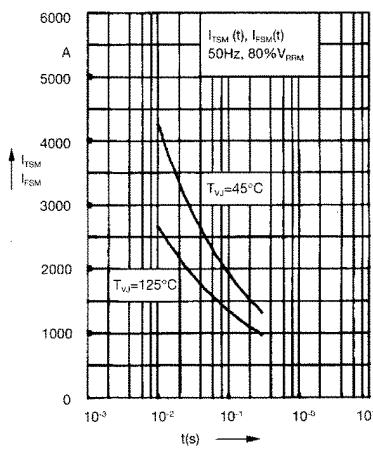


Fig. 1 Surge overload current
 I_{TSM} , I_{FSM} : Crest value, t : duration

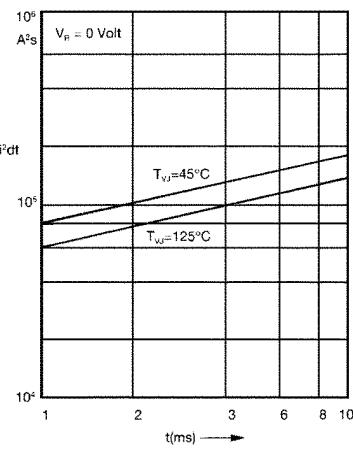


Fig. 2 $\int I^2 dt$ versus time (1-10 ms)

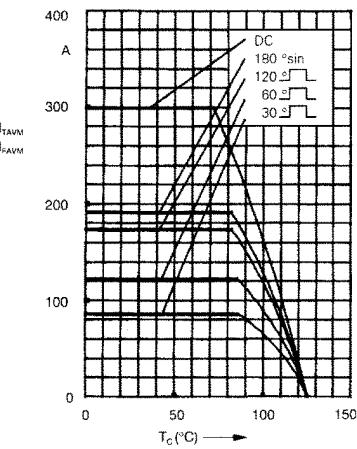


Fig. 2a Maximum forward current at case temperature

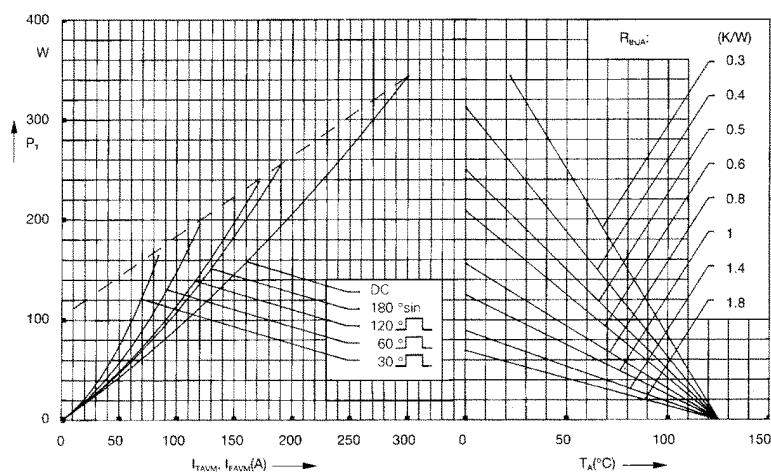


Fig. 3 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

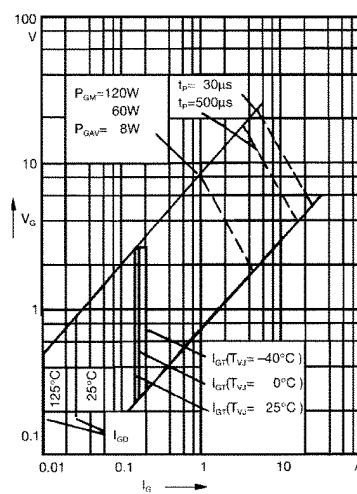


Fig. 4 Gate trigger characteristics

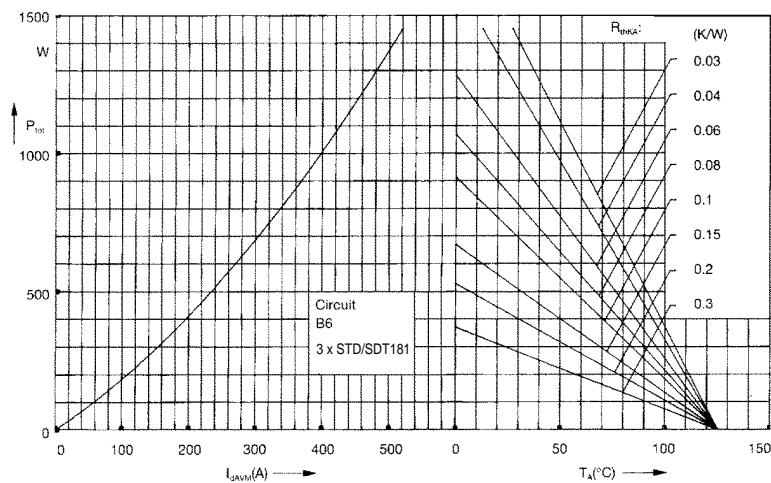


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

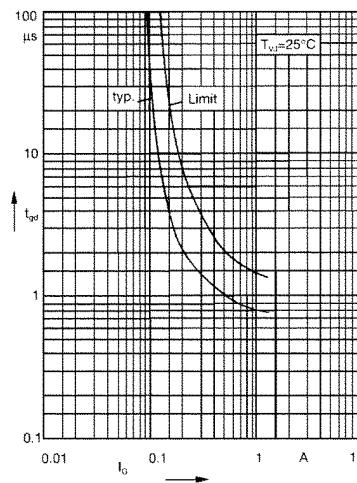


Fig. 6 Gate trigger delay time

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Thyristor-Diode Modules

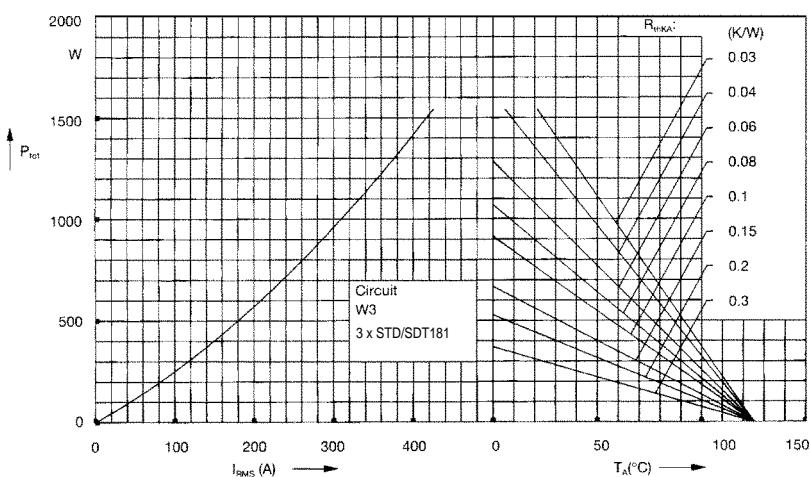


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

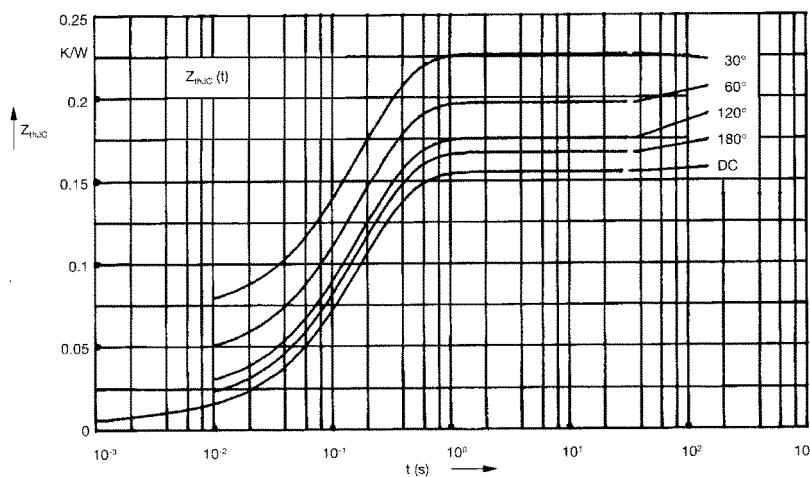


Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.155
180°	0.167
120°	0.176
60°	0.197
30°	0.227

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0072	0.001
2	0.0188	0.08
3	0.129	0.2

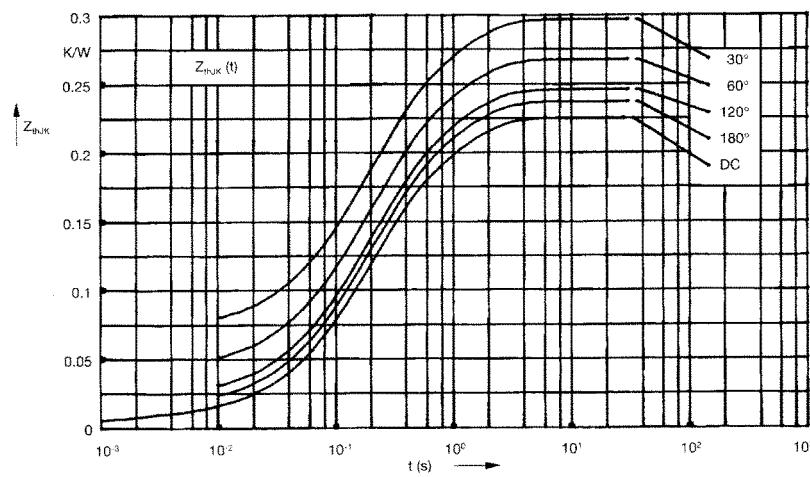


Fig. 9 Transient thermal impedance
junction to heatsink (per thyristor
or diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.225
180°	0.237
120°	0.246
60°	0.267
30°	0.297

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0072	0.001
2	0.0188	0.08
3	0.129	0.2
4	0.07	1.0